IN THE SPECIFICATION

Please replace Table 2 on page 11 with the following amended Table 2:

Mg doped p-type GaN contact layer	0.15µm
Mg doped p-type Al _{0.15} Ga _{0.85} N cladding layer	0.45µm
Mg doped p-type GaN wave guiding layer	0.12µm
Mg doped p-type Al _{0.2} Ga _{0.8} N electron blocking layer	200
In _{0.03} Ga _{0.97} N/In _{0.16} Ga _{0.74} N 3-period MQWs active layer	
In _{0.10} GaN _{0.90} N well layer	35[[□]]
In _{0.03} Ga _{0.97} N barrier layer	50[[□]]
Si doped n-type GaN wave guiding layer	0.12μm
Si doped n-type Al _{0.15} Ga _{0.85} N cladding layer	0.45µm
Si doped n-type In _{0.1} Ga _{0.9} N	500[[□]]
Si doped n-type GaN contact layer	3µm
Un-doped n-type GaN	1µm
Un-doped n-type ELO GaN layer	6µm
Un-doped GaN template layer/Si₃N₄ mask	2µm
GaN buffer	300
Sapphire substrate	450μm

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